

CHILINK N-Channel Enhancement Mode Power MOSFET

Description

The LX3050N combines advanced trench technology to provide excellent $R_{DS(ON)}$, it tailored to minimize conduction loss, and provide superior switching performance. It can be used in wide variety of application.

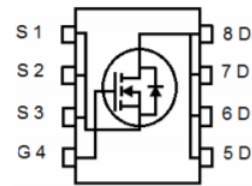
Features

- $V_{DS}=30V$, $I_D=50A$
 $R_{DS(ON)typ.}=6.7m\Omega@V_{GS}=10V$
 $R_{DS(ON)typ.}=9.5m\Omega@V_{GS}=4.5V$
- Fast switching
- High power and current handing capability
- Termination is Lead-free and RoHS Compliant

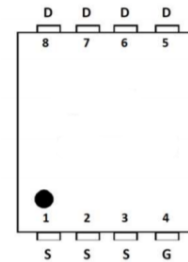


Applications

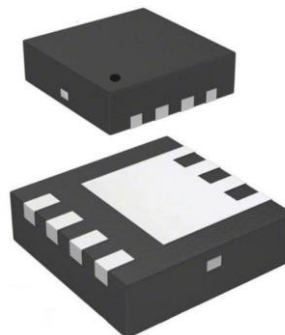
- PWM applications
- Load switch
- Power Management



Schematic Diagram



Pin Assignment



DFN3*3 Package

Maximum Ratings($T_A=25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	$I_D(T_C=25^{\circ}C)$	50	A
	$I_D(T_C=100^{\circ}C)$	33	
Pulsed Drain Current ^B	I_{DM}	200	A
Maximum Power Dissipation ^A	P_D	12	W
Single pulse avalanche energy	E_{AS}	36	mJ
Junction and Storage Temperature Range	T_J, T_{STG}	-55 To 150	$^{\circ}C$

Thermal Characteristic

Thermal Resistance, Junction to Ambient	R_{QJA}	3.8	$^{\circ}\text{C/W}$
---	-----------	-----	----------------------

Electrical Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Test conditions	MIN	TYP	MAX	UNIT
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	30			V
Gate-Threshold Voltage	V _{th(GS)}	V _{DS} = V _{GS} , I _D =250 uA	1	1.5	2.2	V
Gate-body Leakage	IGSS	V _{DS} =0V, V _{GS} =±20V			±100	nA
Zero Gate Voltage Drain Current	IDSS	V _{DS} =30V, V _{GS} =0V			1	uA
Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =5A		6.7	8	mΩ
		V _{GS} =4.5V, I _D =4A		9.2	14	mΩ
Forward Transconductance	g _{FS}	V _{DS} =5V, I _D =5A	10			s
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} = 15V, V _{GS} =0V, F=1MHz		1140		pF
Output Capacitance	C _{oss}			175		
Reverse Transfer Capacitance	C _{rss}			151		
Switching Capacitance						
Turn-on Delay Time	t _{d(on)}	V _{DD} = 15V, R _L =3Ω V _{GS} = 10V, R _{GEN} =3Ω		15		nS
Turn-on Rise Time	t _r			19		nS
Turn-off Delay Time	t _{d(off)}			35		nS
Turn-off Fall Time	t _f			21		nS
Total Gate Charge	Q _g	V _{DS} = 15V, I _D =5A, V _{GS} =4.5V		14		nC
Gate-Source Charge	Q _{gs}			3		nC
Gate-Drain Charge	Q _{gd}			5		nC
Drain-Source Diode Characteristics						
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _D =5A			1.2	V
Diode Forward Current	I _s				50	A

Notes:

- The Power dissipation P_D is based on $T_{J(MAX)}=150^{\circ}\text{C}$, using $\leq 10s$ junction-to ambient thermal resistance.
- Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}=150^{\circ}\text{C}$. Ratings are based on low frequency and duty cycles to keep initial $T_J=25^{\circ}\text{C}$.
- The Static characteristics in Figures are obtained using $<300\mu s$ pulses, duty cycle 2% max.
- EAS condition: $T_J=25^{\circ}\text{C}, V_{DD}=15V, V_{GS}=10V, R_G=25\Omega, L=0.5Mh$.

Typical Electrical and Thermal Characteristics

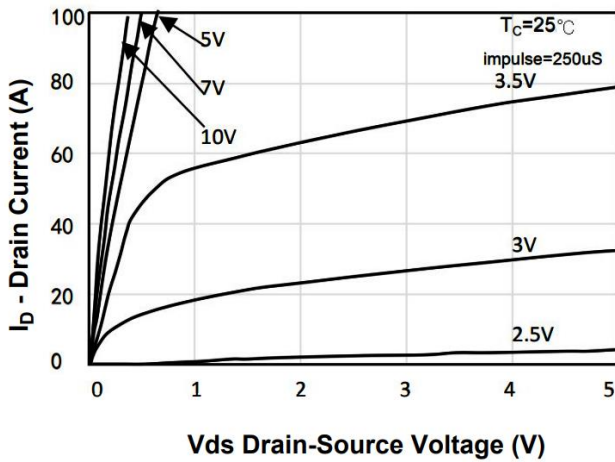


Figure 1. On-Region Characteristics

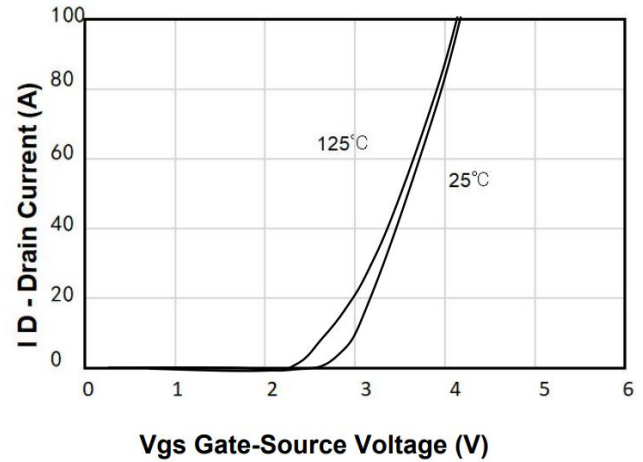


Figure 2. Transfer Characteristics

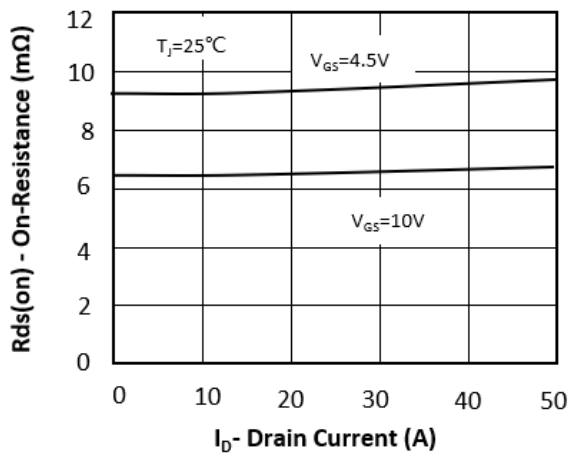


Figure 3. On-resistance vs. Drain Current

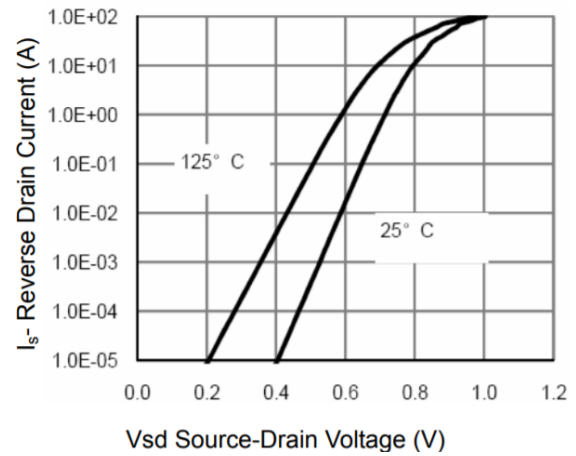


Figure 4. Body Diode Characteristics

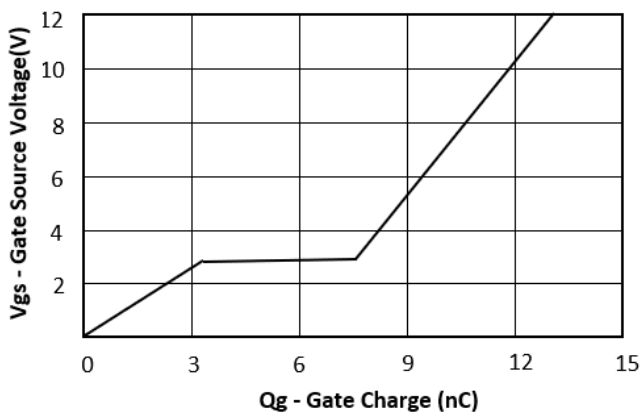


Figure 5. Gate Charge Characteristics

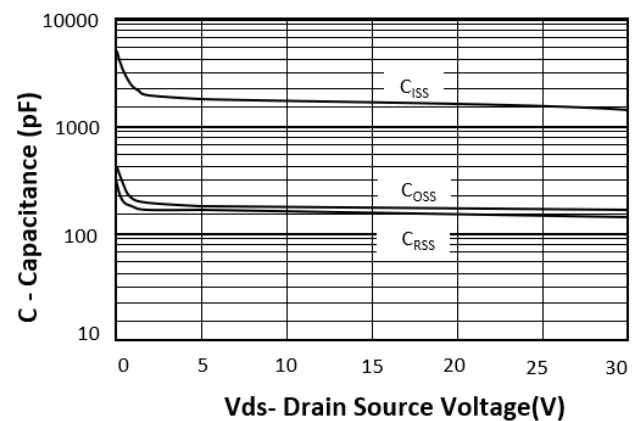


Figure 6. Capacitance Characteristics

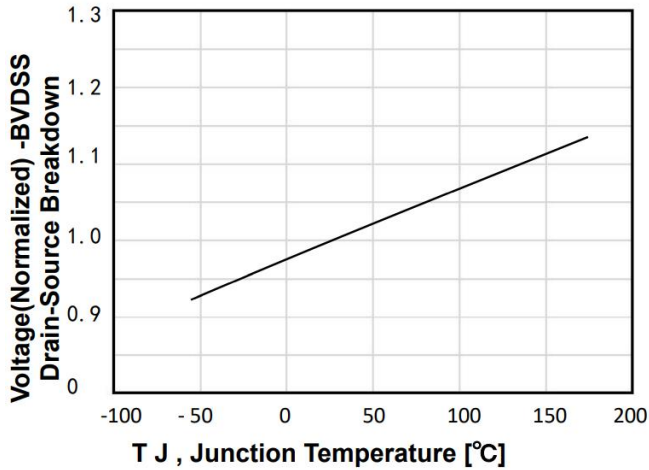


Figure 7. Breakdown Voltage Variation vs Temperature

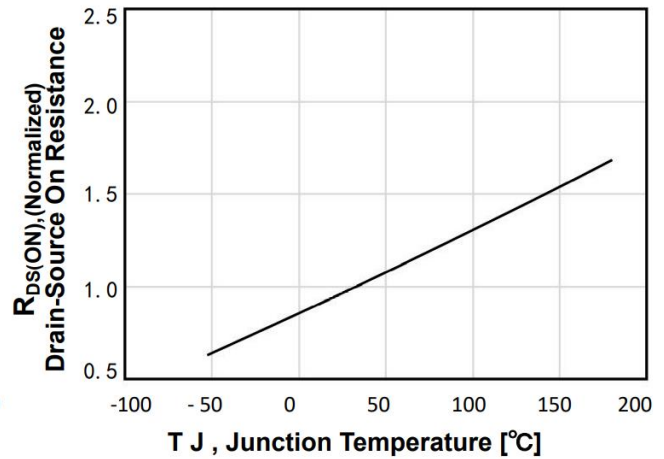


Figure 8. On-Resistance Variation vs Temperature

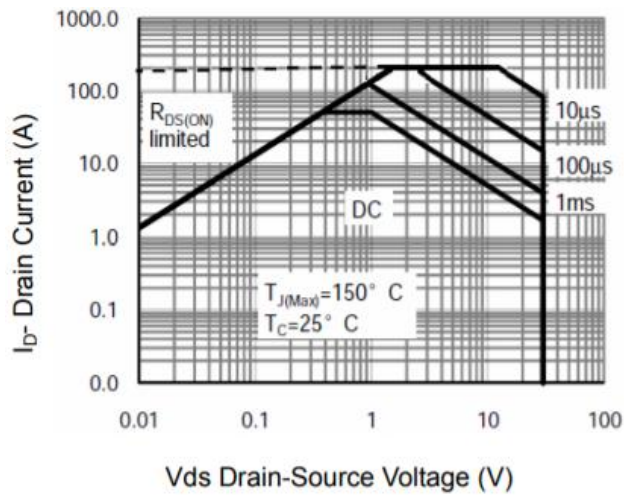


Figure 9. Safe Operation Area

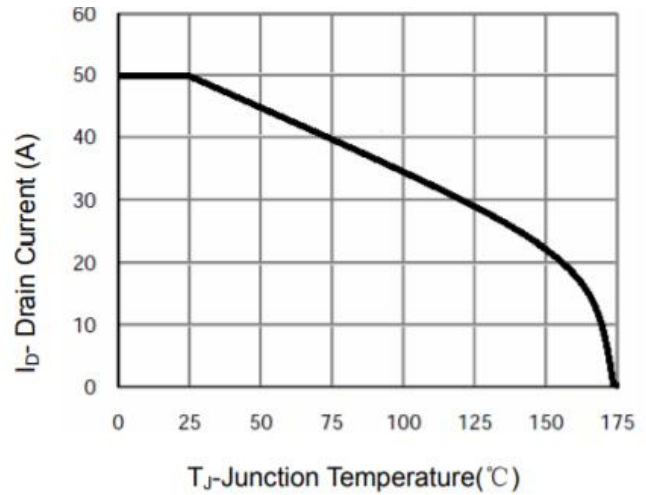


Figure 10. Current – Junction Temperature

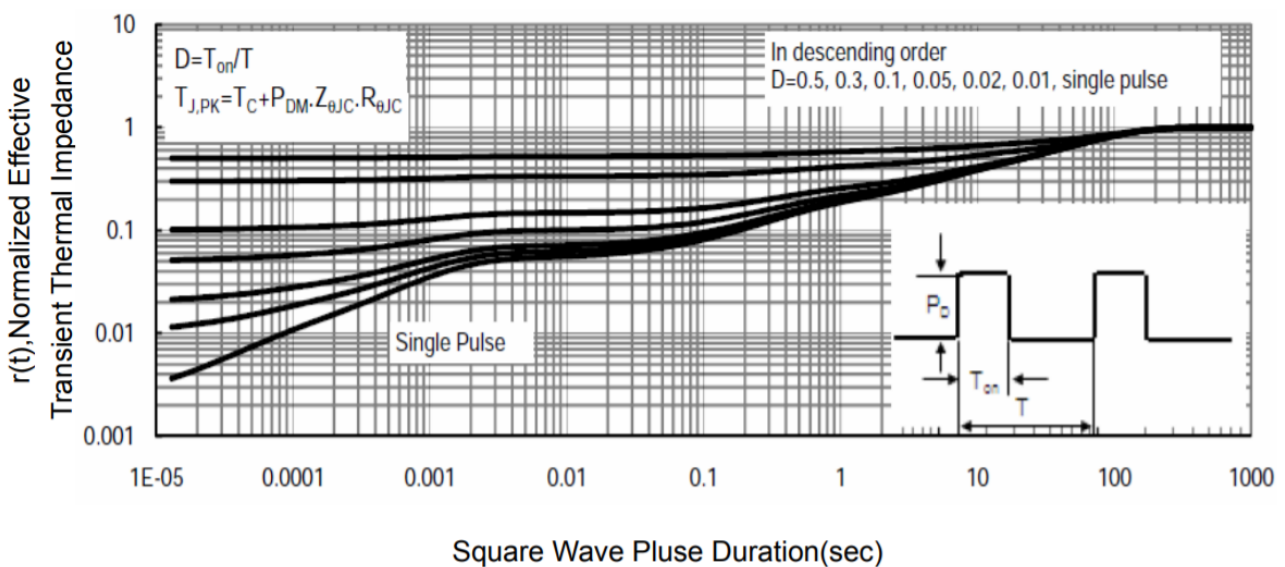
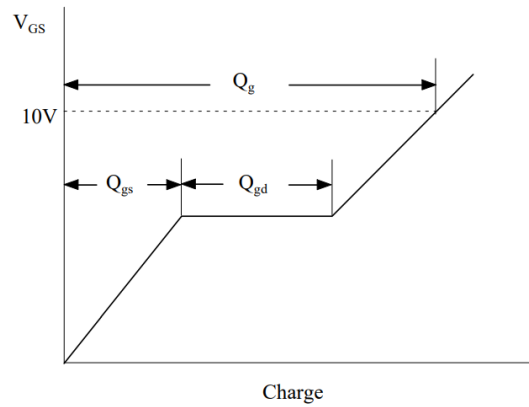
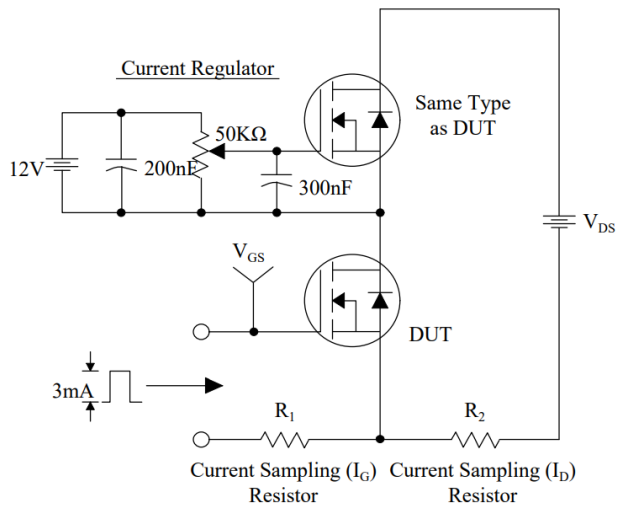
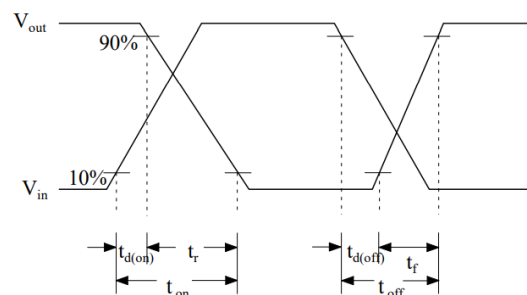
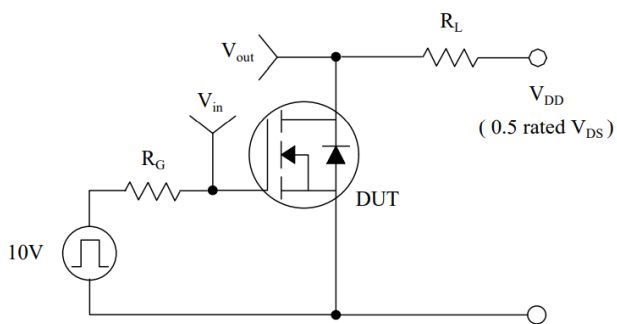


Figure 11 Normalized Maximum Transient Thermal Impedance

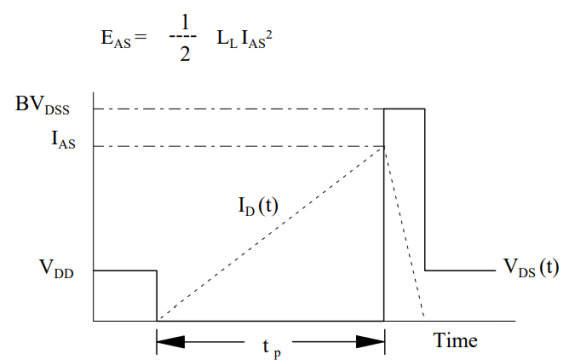
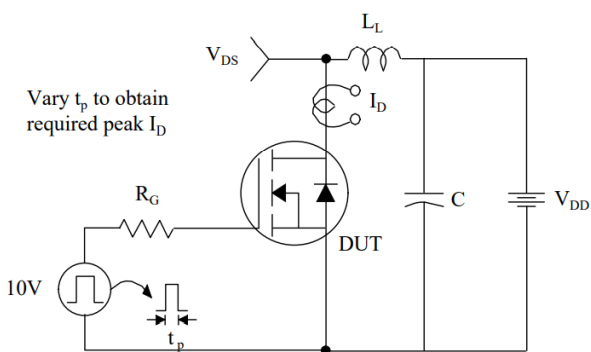
Gate Charge Test Circuit & Waveform



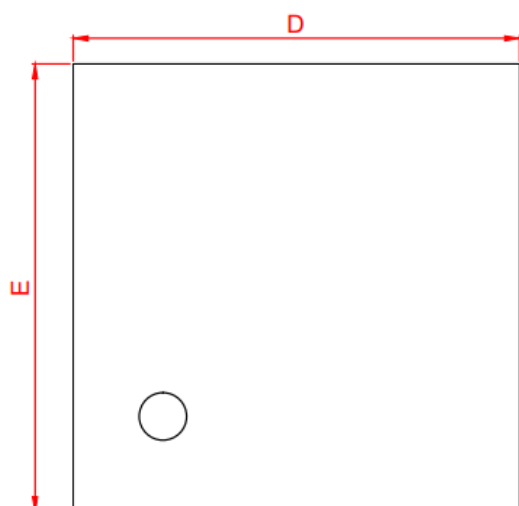
Resistive Switching Test Circuit & Waveforms



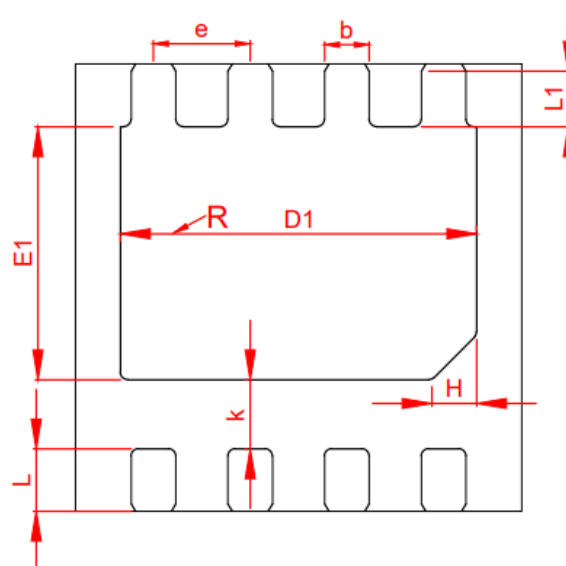
Unclamped Inductive Switching Test Circuit & Waveforms



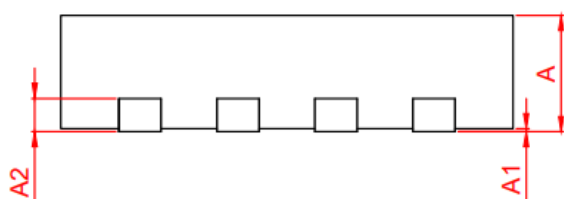
DFN3*3 Package Information



TOP VIEW



BOTTOM VIEW



SIDE VIEW

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.70	0.75	0.80
* A1	0.00	0.02	0.05
* b	0.27	0.32	0.37
* A2	0.20REF		
* D	2.90	3.00	3.10
* E	2.90	3.00	3.10
* E1	1.70	1.80	1.90
* D1	2.35	2.45	2.55
* e	0.65BSC		
* L	0.35	0.40	0.45
h	0.30 REF		
* k	0.50REF		
* L1	0.25	0.30	0.35

THIS PRODUCT HAS BEEN DESIGNED AND QUALIFIED FOR THE CONSUMER MARKET. APPLICATIONS OR USES AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS ARE NOT AUTHORIZED.

CHIPLINK DOES NOT ASSUME ANY LIABILITY ARISING OUT OF SUCH APPLICATIONS OR USES OF ITS PRODUCTS.

THIS DOCUMENT SUPERSEDES AND REPLACES ALL INFORMATION PREVIOUSLY SUPPLIED.

CHIPLINK RESERVES THE RIGHT TO IMPROVE PRODUCT DESIGN, FUNCTIONS AND RELIABILITY WITHOUT NOTICE.